

Title (en)
METHOD FOR REACTIVE SPUTTERING

Title (de)
REAKTIVES SPUTTERVERFAHREN

Title (fr)
PROCÉDÉ DE PULVÉRISATION CATHODIQUE RÉACTIVE

Publication
EP 2478126 A1 20120725 (EN)

Application
EP 10763585 A 20100727

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Abstract (en)
[origin: WO2011012093A1] The invention is related to the method of creating protective and functional layers using the PVD method, from a cathode with reduced surface electrical conductivity, by way of application from the working coating source where the principle is that the material is applied to the substrate (6) from the working coating source designed as a rotating working cathode (2) wherein the rotating working cathode (2) is coated during the process from the auxiliary coating source with material with sufficient electrical conductivity where the layer of the coating applied to the surface of the rotating working cathode (2) has greater electrical conductivity than the surface of this rotating working cathode (2) created during the processes without coating of the rotating working cathode using the auxiliary coating source.

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